

Figure 1

**SmartPhone™**

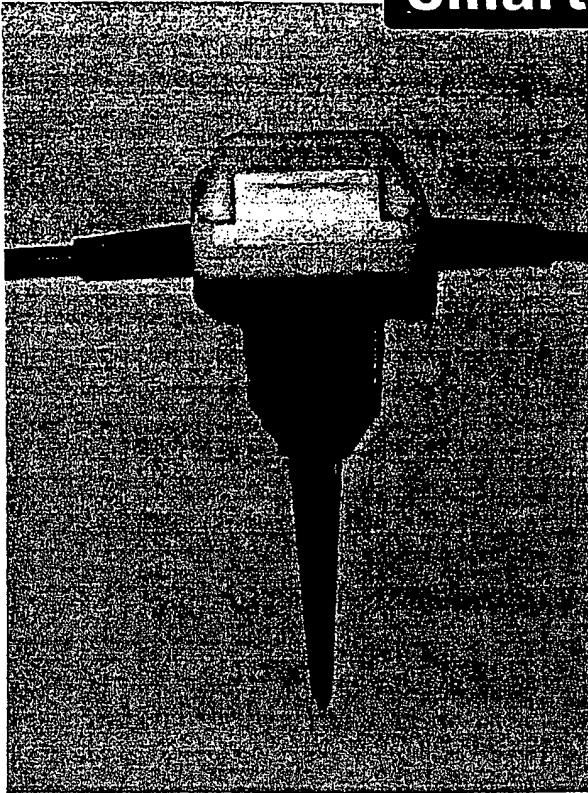


Figure 2A

**Assembled  
SmartPhone™**

**SmartPhone™ with  
Cover Removed**

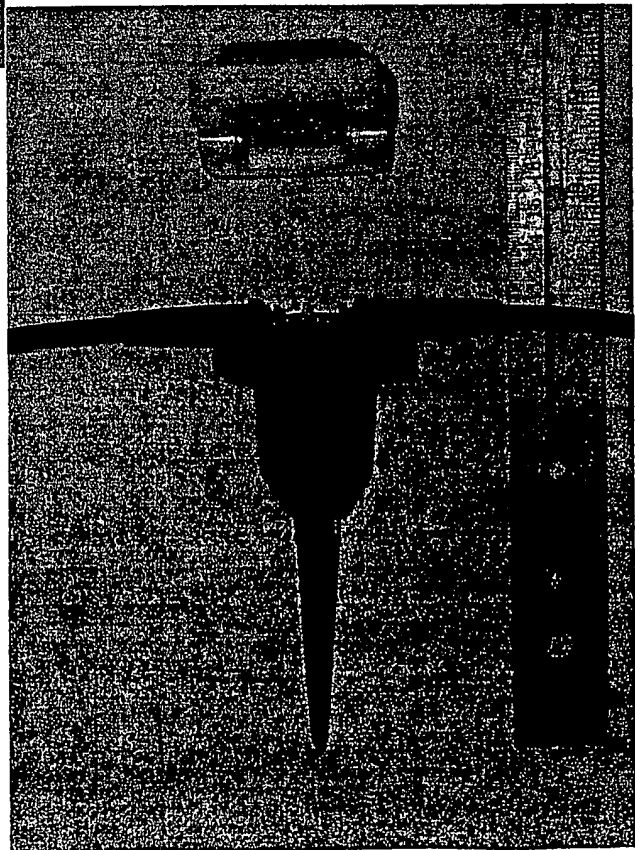


Figure 2B

10017961.120701

10017961-120701

**Interface Board  
Assembly**

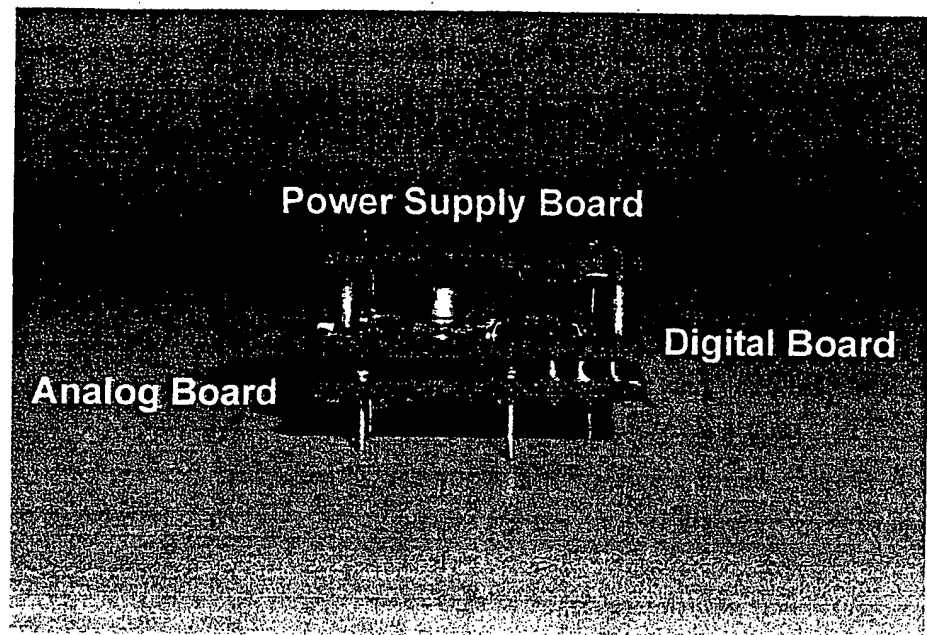
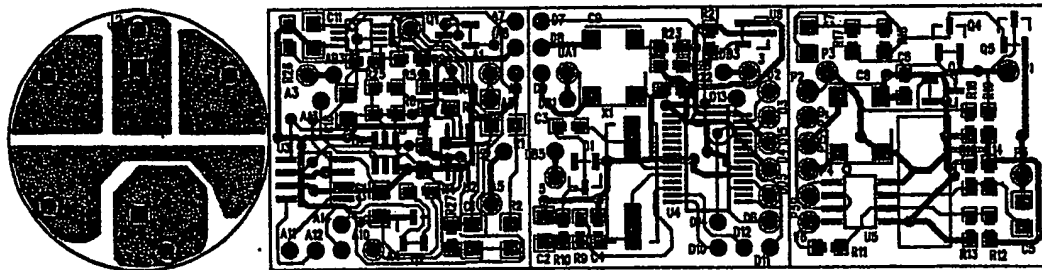


Figure 3

10017961-120701



ANALOG  
+5A  
AGND

DIGITAL  
+5D  
DGND

POWER  
+5C  
CGND  
XCV

- NOTES:
1. ANALOG AND DIGITAL FOLD CIRCUIT SIDES TOGETHER
  2. POWER AND DIGITAL FOLD COMPONENT SIDES TOGETHER
  3. WHEN FOLDED X1 COMPONENT ON DIGITAL BOARD SHOULD FOLD OVER A BLANK AREA ON POWER BOARD.
  4. TP1...TP5 WILL HOLD PINS THAT PLUG INTO JUG BOARD.
  5. SIGNALS SENSOR+ AND SENSOR- (TP1 & TP2):
    - A. MUST BE ROUTED TOGETHER.
    - B. MUST BE KEPT AWAY FROM OTHER SIGNALS.
    - C. SHOULD BE 'SHIELDED' WITH AN AGND LAND

Figure 4

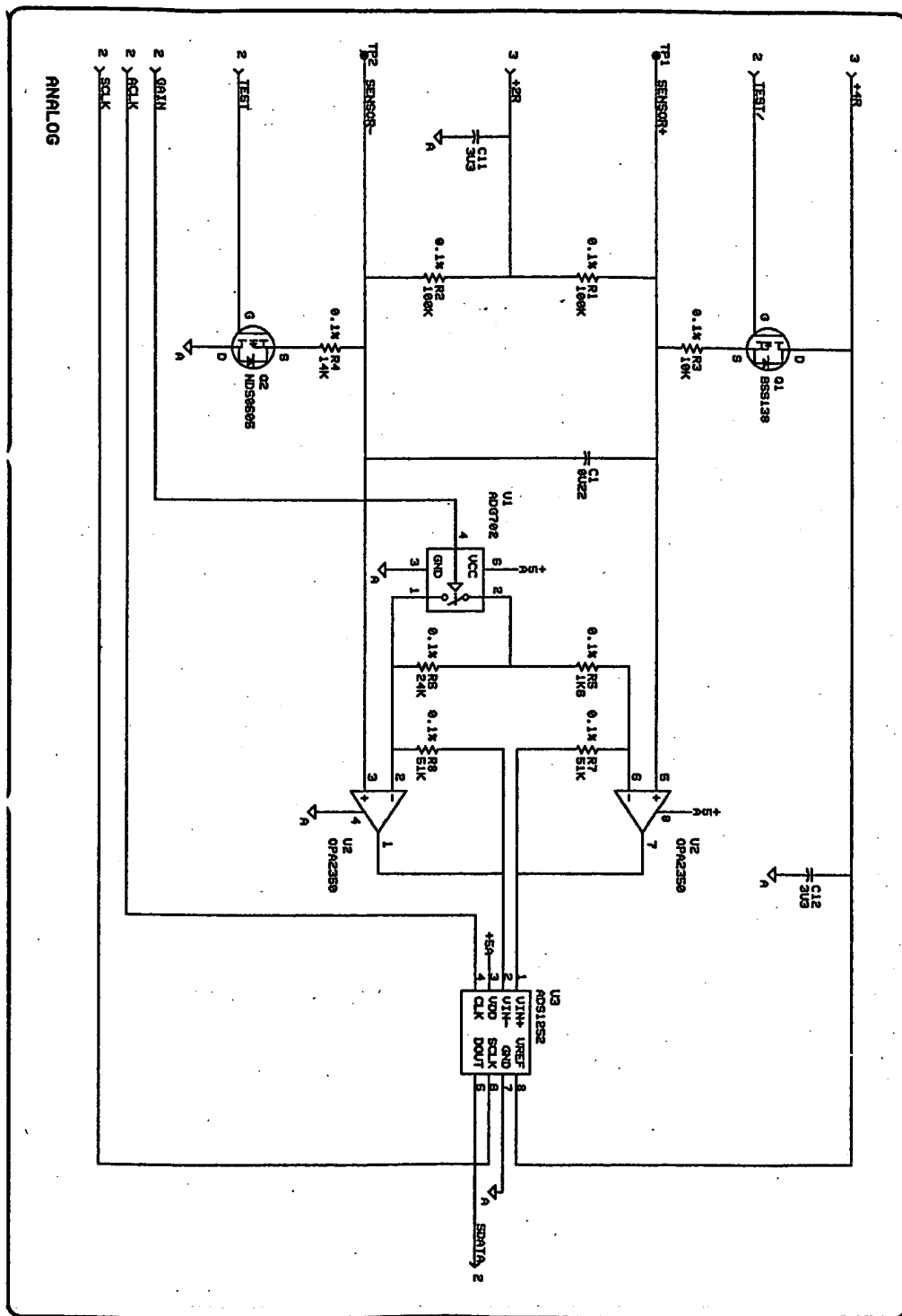
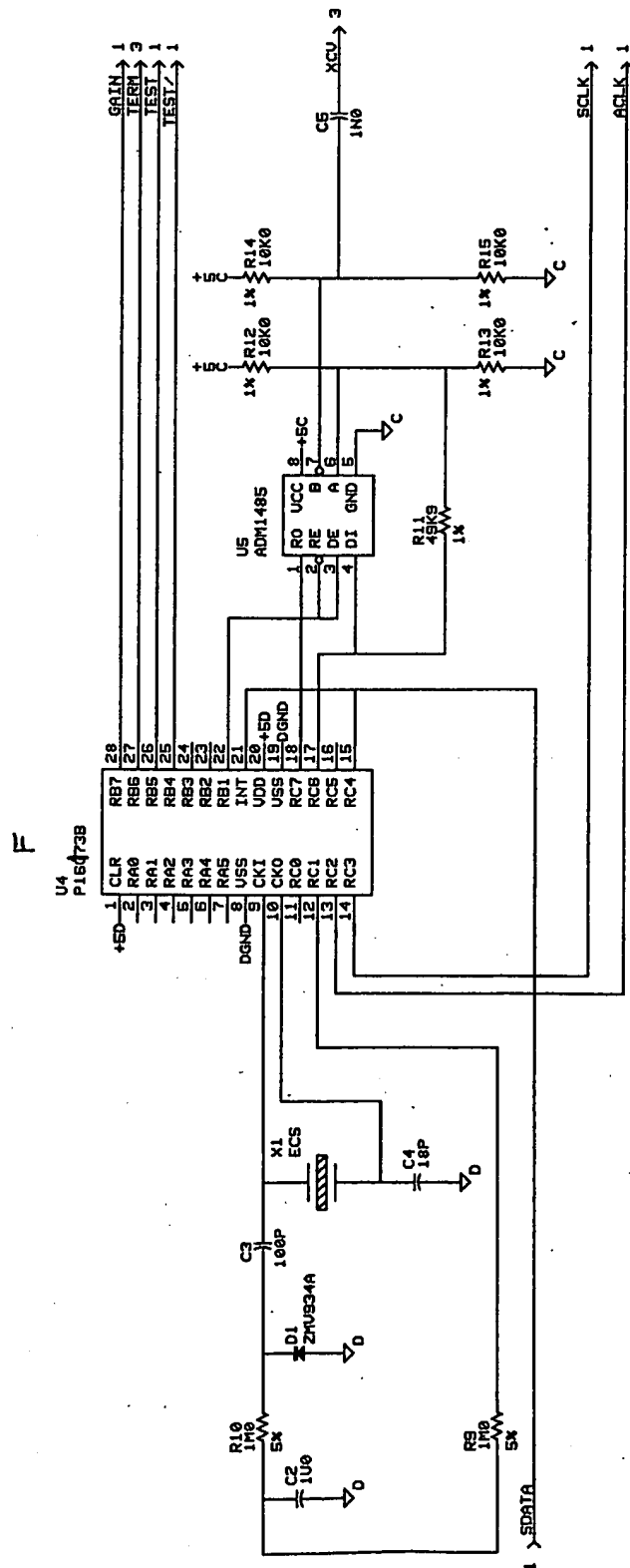


Figure 5

10017951.120701

[illegible]

# DIGITAL

Figure 6

FOOTPRINT

SYSTEM AND METHOD FOR GATHERING SEISMIC DATA

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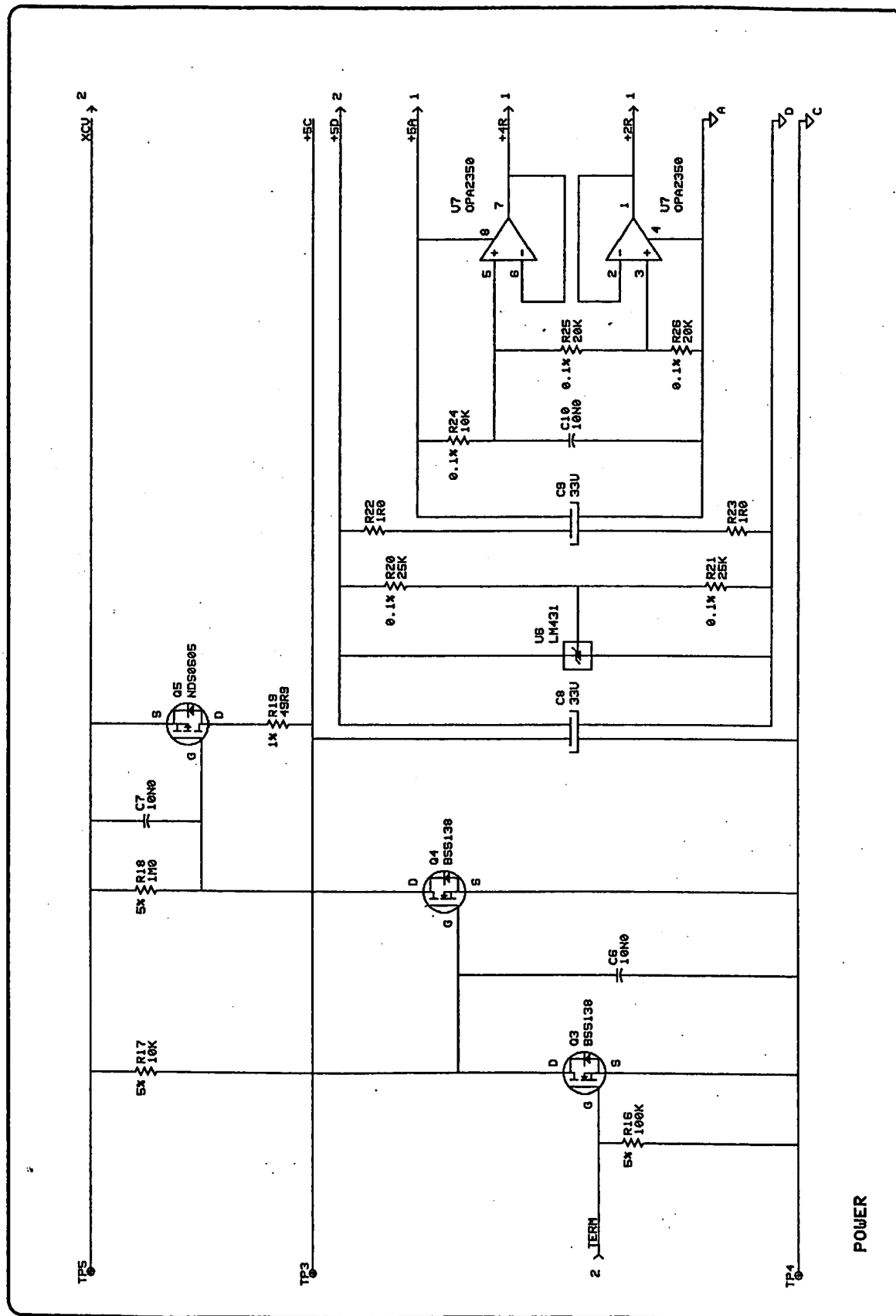


Figure 7

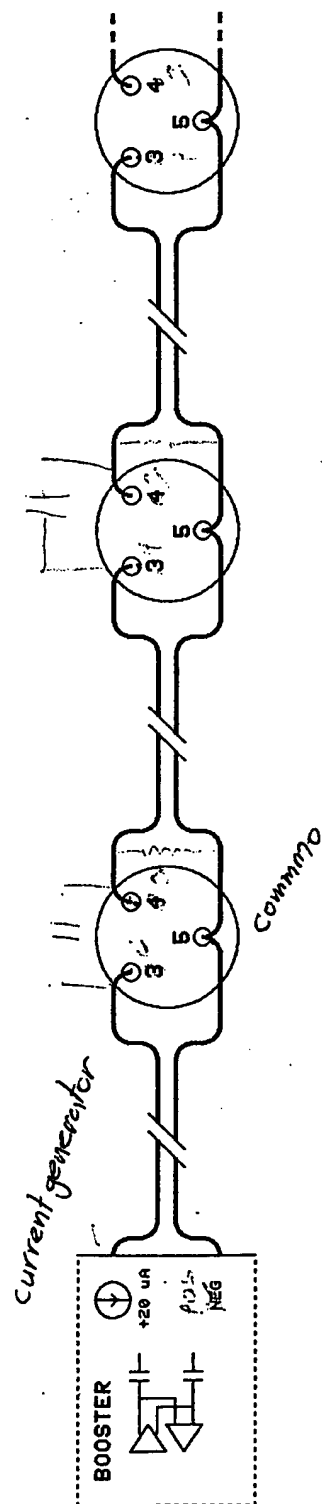


Figure 8



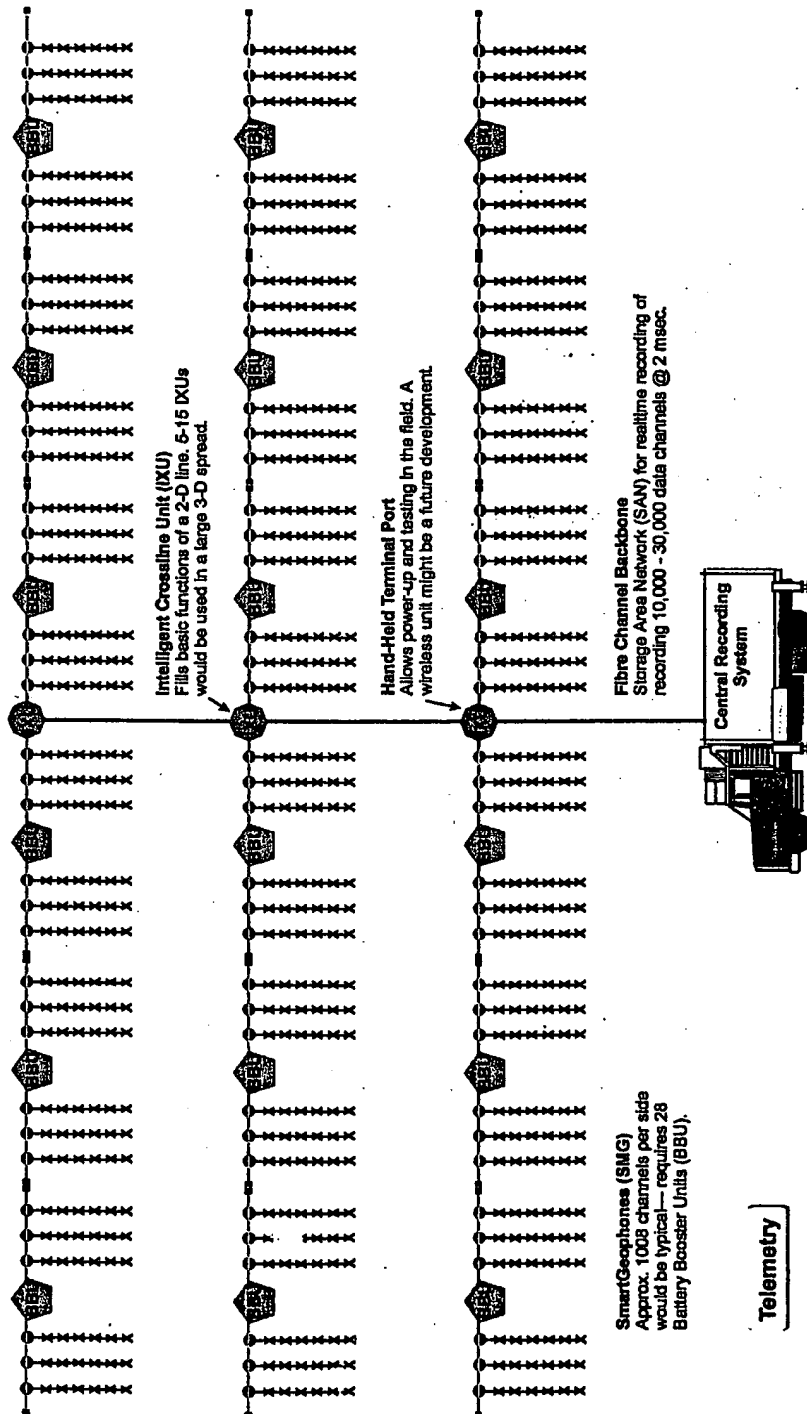


Figure 9